

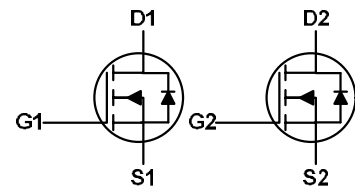
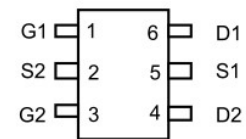
➤ General Description

This PAN6208C Dual N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent $R_{ds(On)}$ performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

➤ Feature

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- TSOP-6 package design

➤ TSOP-6



➤ Absolute Maximum Ratings

| Parameter | Symbol | Rating | | Units |
|---|----------------------|------------|--------------|-------|
| | | 10s | Steady State | |
| Drain-Source Voltage | V_{DS} | 60 | | V |
| Gate-Source Voltage | V_{GS} | ±20 | | V |
| Continuous Drain Current, $V_{GS} @ 10V^1$ | $I_D@T_A=25^\circ C$ | 2.8 | 2.5 | A |
| Continuous Drain Current, $V_{GS} @ 10V^1$ | $I_D@T_A=70^\circ C$ | 2.2 | 2 | A |
| Pulsed Drain Current ² | I_{DM} | 15 | | A |
| Total Power Dissipation ³ | $P_D@T_A=25^\circ C$ | 1.5 | 1.1 | W |
| Storage Temperature Range | T_{STG} | -55 to 150 | | °C |
| Operating Junction Temperature Range | T_J | -55 to 150 | | °C |
| Thermal Resistance Junction-Ambient ¹ | $R_{\theta JA}$ | 110 | | °C/W |
| Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$) | $R_{\theta JA}$ | 85 | | °C/W |
| Thermal Resistance Junction-Case ¹ | $R_{\theta JC}$ | 70 | | °C/W |

➤ Electrical Characteristics ($T_J=25^\circ C$ Unless otherwise noted)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|--|------------------------------|---|------|-------|-----------|---------------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 60 | --- | --- | V |
| BV_{DSS} Temperature Coefficient | $\Delta BV_{DSS}/\Delta T_J$ | Reference to $25^\circ C, I_D=1mA$ | --- | 0.054 | --- | $V/^\circ C$ |
| Static Drain-Source On-Resistance ² | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=2A$ | --- | --- | 100 | m Ω |
| | | $V_{GS}=4.5V, I_D=1A$ | --- | --- | 110 | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{GS}=V_{DS}, I_D=250\mu A$ | 1.2 | --- | 2.5 | V |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}$ | | --- | -4.96 | --- | $mV/^\circ C$ |
| Drain-Source Leakage Current | I_{DSS} | $V_{DS}=48V, V_{GS}=0V, T_J=25^\circ C$ | --- | --- | 1 | μA |
| | | $V_{DS}=48V, V_{GS}=0V, T_J=55^\circ C$ | --- | --- | 5 | |
| Gate-Source Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | --- | --- | ± 100 | nA |
| Forward Transconductance | g_{fs} | $V_{DS}=5V, I_D=2A$ | --- | 13.2 | --- | S |
| Total Gate Charge (4.5V) | Q_g | $V_{DS}=48V, V_{GS}=4.5V, I_D=2A$ | --- | 5 | --- | nC |
| Gate-Source Charge | Q_{gs} | | --- | 1.61 | --- | |
| Gate-Drain Charge | Q_{gd} | | --- | 1.96 | --- | |
| Turn-On Delay Time | $T_{d(on)}$ | $V_{DS}=30V, V_{GS}=10V, R_G=3.3\Omega, I_D=2A$ | --- | 2 | --- | ns |
| Rise Time | T_r | | --- | 23.8 | --- | |
| Turn-Off Delay Time | $T_{d(off)}$ | | --- | 12.4 | --- | |
| Fall Time | T_f | | --- | 19.6 | --- | |
| Input Capacitance | C_{iss} | $V_{DS}=15V, V_{GS}=0V, f=1MHz$ | --- | 511 | --- | pF |
| Output Capacitance | C_{oss} | | --- | 38 | --- | |
| Reverse Transfer Capacitance | C_{rss} | | --- | 25 | --- | |

➤ Diode Characteristics

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|--|----------|--|------|------|------|------|
| Continuous Source Current ^{1,4} | I_S | $V_G=V_D=0V, \text{Force Current}$ | --- | --- | 2.5 | A |
| Pulsed Source Current ^{2,4} | I_{SM} | | --- | --- | 15 | A |
| Diode Forward Voltage ² | V_{SD} | $V_{GS}=0V, I_S=1A, T_J=25^\circ C$ | --- | --- | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $I_F=2A, di/dt=100A/\mu s, T_J=25^\circ C$ | --- | 10.5 | --- | nS |
| Reverse Recovery Charge | Q_{rr} | | --- | 6 | --- | nC |

Note :

- 1.Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.Ensure that the channel temperature does not exceed $150^\circ C$.
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

➤ Typical Characteristics

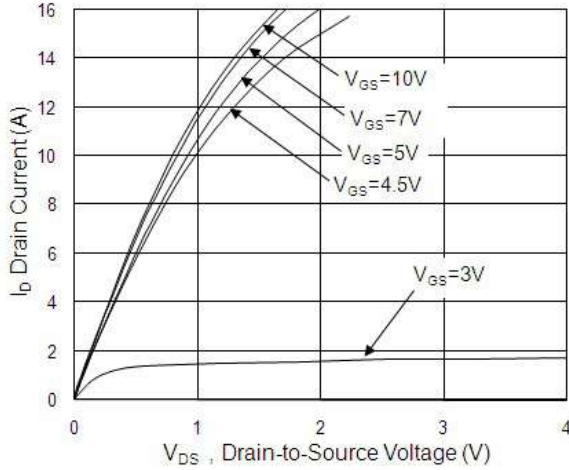


Fig.1 Typical Output Characteristics

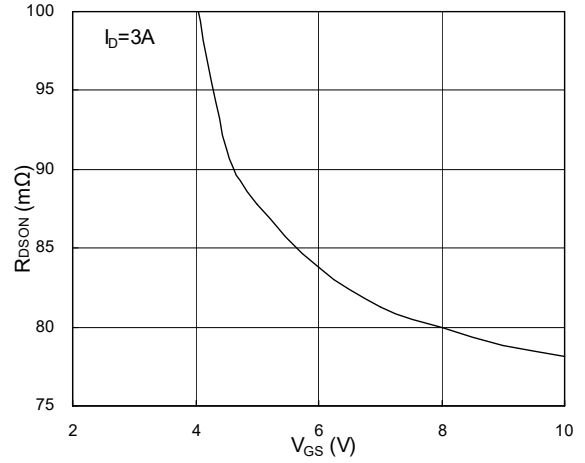


Fig.2 On-Resistance v.s Gate-Source

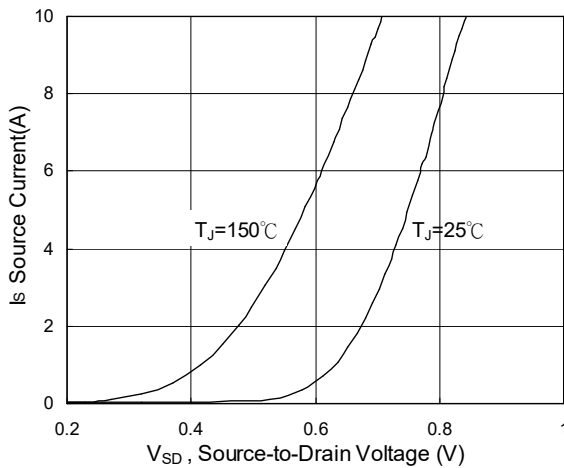


Fig.3 Forward Characteristics of Reverse

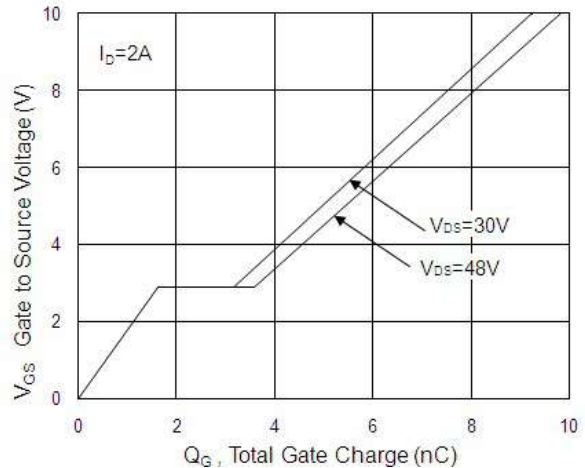


Fig.4 Gate-Charge Characteristics

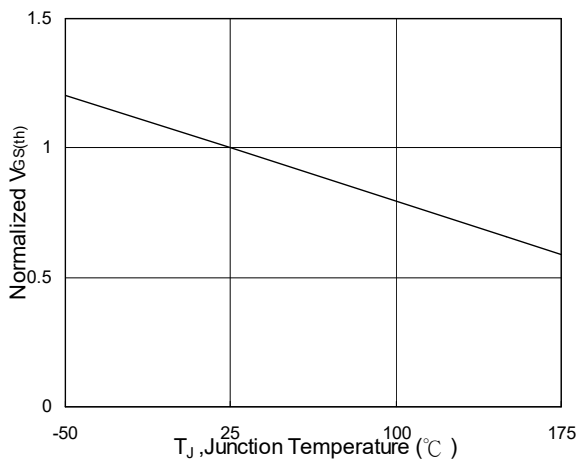


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

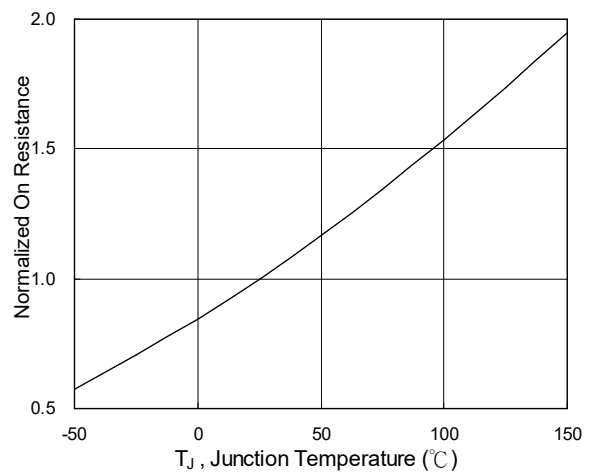


Fig.6 Normalized $R_{DS(ON)}$ v.s T_J

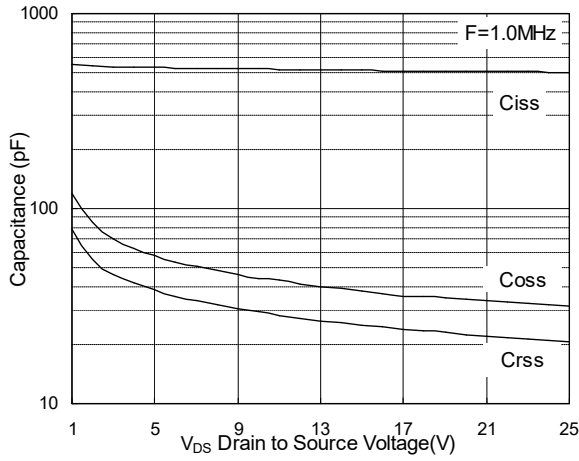


Fig.7 Capacitance

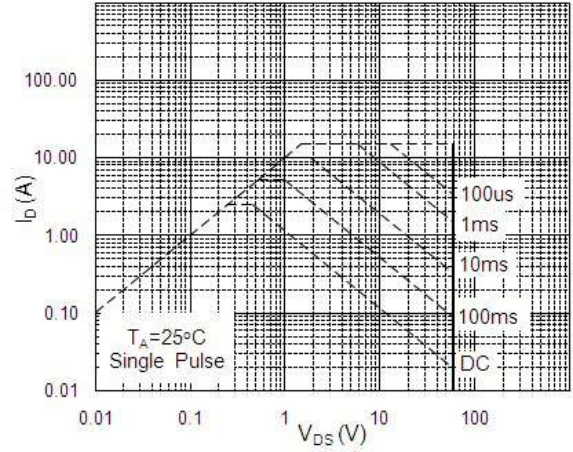


Fig.8 Safe Operating Area

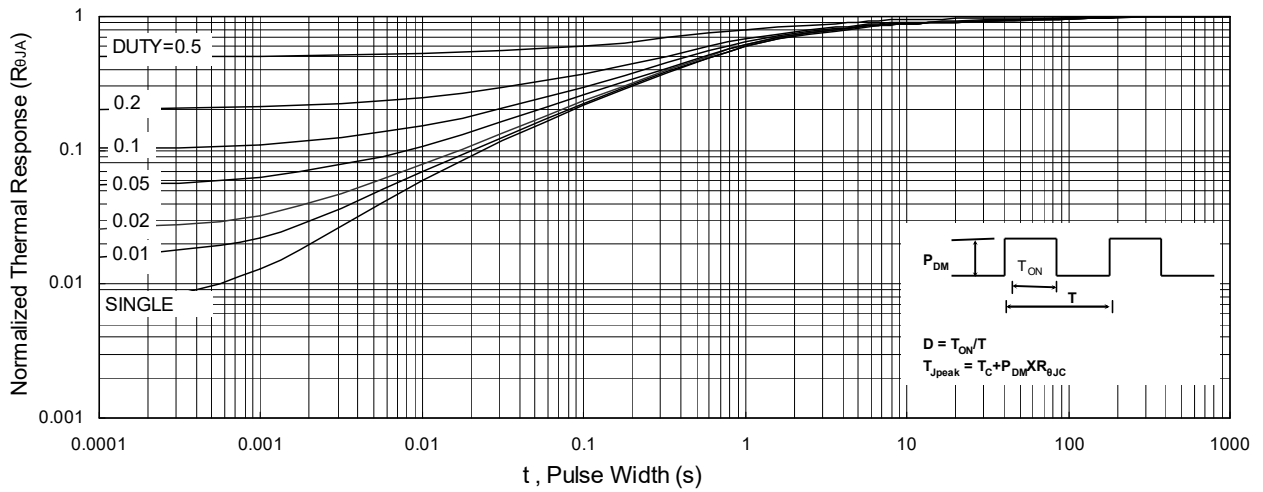


Fig.9 Normalized Maximum Transient Thermal Impedance

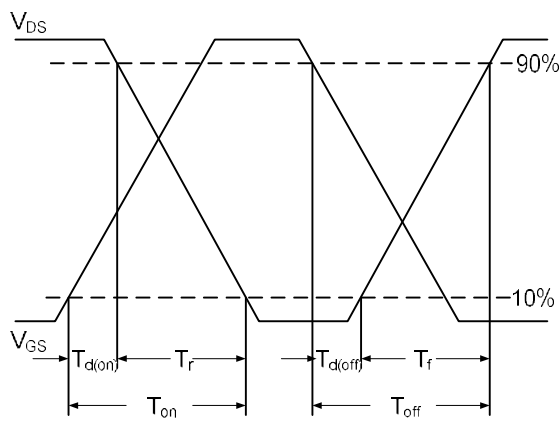


Fig.10 Switching Time Waveform

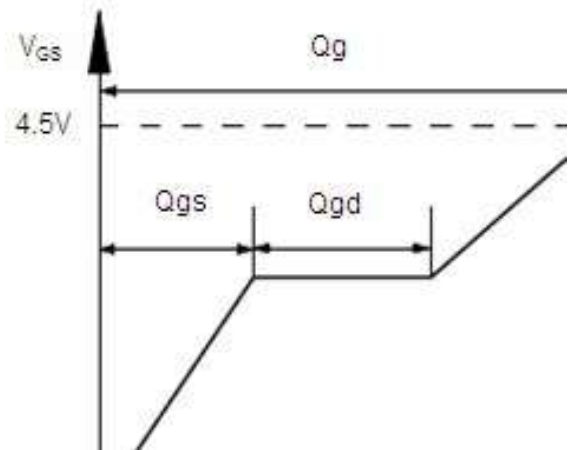
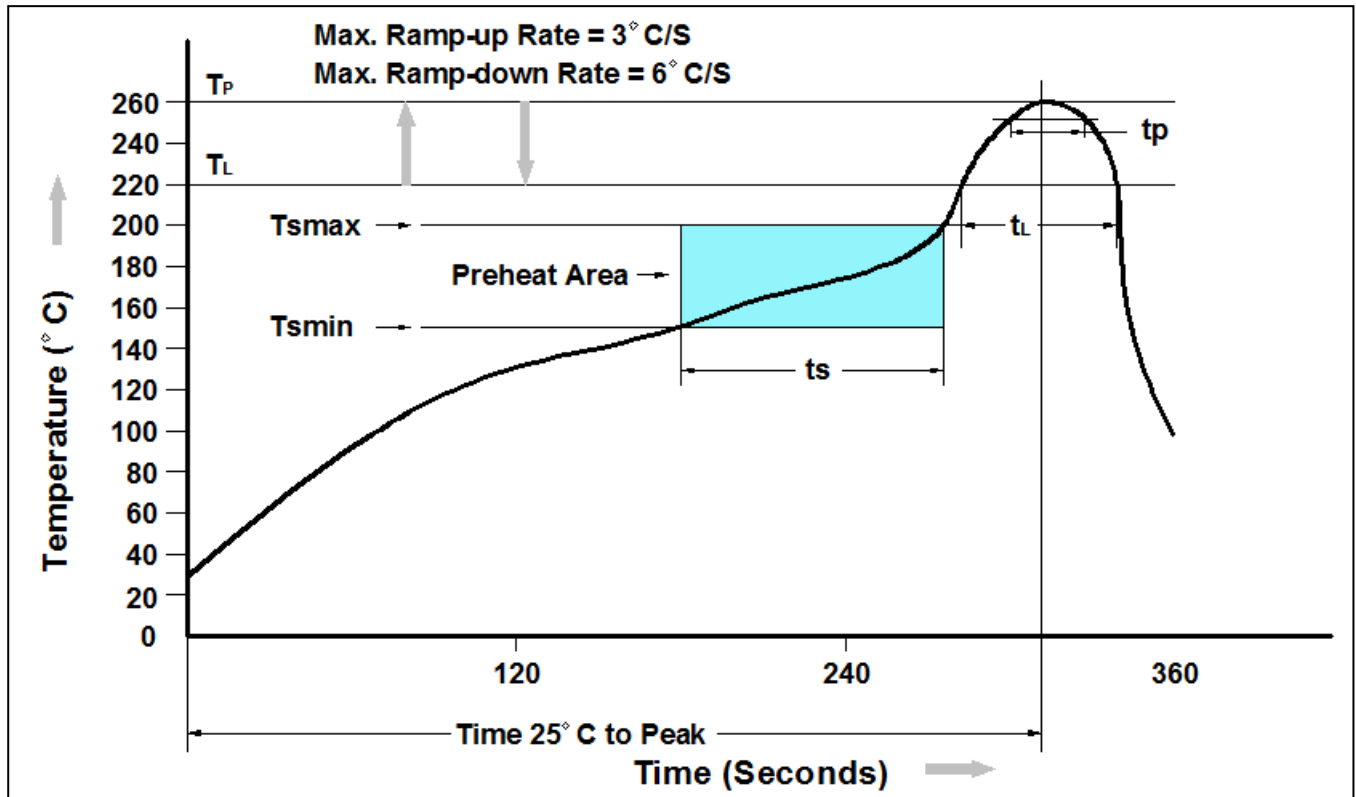


Fig.11 Gate Charge Waveform

➤ Recommand IR Reflow Soldering Thermal Profile

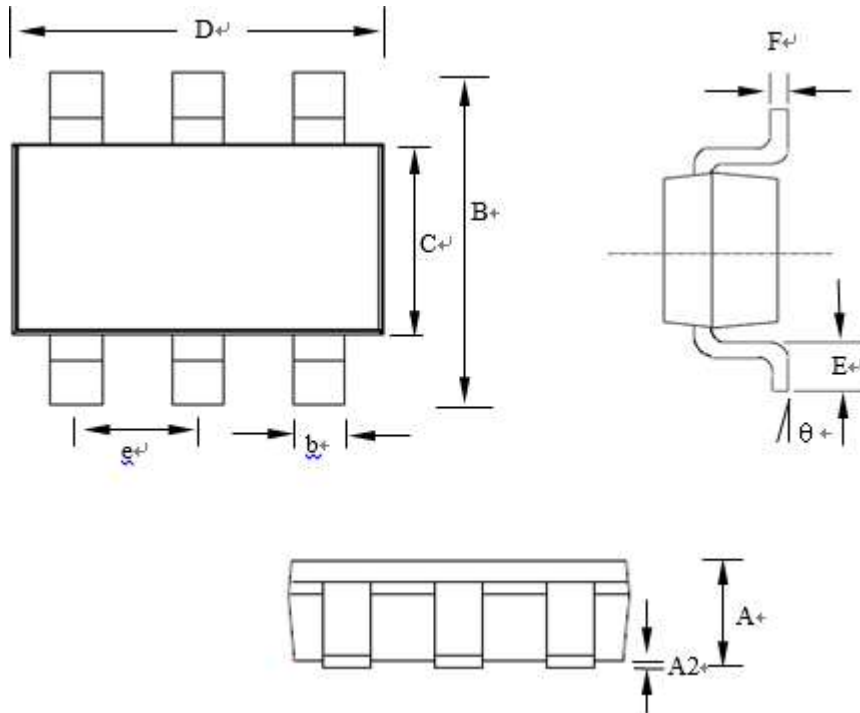


| Profile Feature | Pb-Free Assembly Profile |
|--|--------------------------|
| Temperature Min. (T_{smin}) | 150°C |
| Temperature Max. (T_{smax}) | 200°C |
| Time (t_s) from (T_{smin} to T_{smax}) | 60-120 seconds |
| Average Ramp-up Rate (t_L to t_P) | 3°C/second max. |
| Liquidous Temperature (T_L) | 217°C |
| Time (t_L) Maintained Above (T_L) | 60 – 150 seconds |
| Peak Temperature | 260°C +0°C / -5°C |
| Time (t_P) within 5°C of actual Peak Temperature | 30 seconds |
| Ramp-down Rate (T_P to T_L) | 6°C/second max |
| Time 25°C to Peak Temperature | 8 minutes max. |

➤ Ordering Information

| Part Number | Description | Quantity |
|-------------|-------------|----------|
| PAN6208C | TSOP-6 Reel | 3000 pcs |

➤ Package Information (TSOP-6)



| SYMBOLS | MILLIMETERS | | | INCHES | | |
|----------|-------------|-------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.70 | -- | 0.9 | 0.028 | -- | 0.035 |
| A2 | 0.00 | -- | 0.10 | 0.000 | -- | 0.004 |
| B | 2.60 | 2.80 | 3.00 | 0.102 | 0.110 | 0.118 |
| C | 1.40 | 1.60 | 1.80 | 0.055 | 0.063 | 0.071 |
| D | 2.70 | 2.90 | 3.10 | 0.106 | 0.114 | 0.122 |
| E | 0.30 | 0.40 | 0.60 | 0.012 | 0.016 | 0.024 |
| F | 0.07 | 0.127 | 0.20 | 0.003 | 0.005 | 0.008 |
| b | 0.30 | 0.40 | 0.50 | 0.012 | 0.016 | 0.020 |
| e | -- | 0.95 | -- | -- | 0.037 | -- |
| θ | 0° | 5° | 10° | 0° | 5° | 10° |

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